

# 74HC126; 74HCT126

Quad buffer/line driver; 3-state

Rev. 3 — 22 September 2014

Product data sheet

## 1. General description

The 74HC126; 74HCT126 is a quad buffer/line driver with 3-state outputs controlled by the output enable inputs (nOE). A LOW on nOE causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

## 2. Features and benefits

- Inverting outputs
- Complies with JEDEC standard no. 7A
- Input levels:
  - ◆ For 74HC126: CMOS level
  - ◆ For 74HCT126: TTL level
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC126N	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
74HCT126N				
74HC126D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74HCT126D				
74HC126DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74HCT126DB				
74HC126PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74HCT126PW				



## 4. Functional diagram

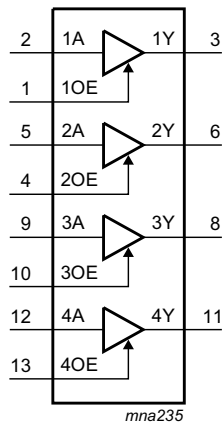


Fig 1. Logic symbol

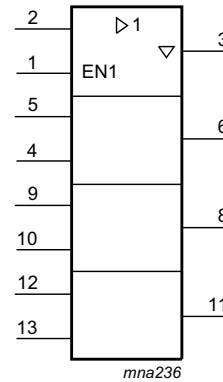


Fig 2. IEC logic symbol

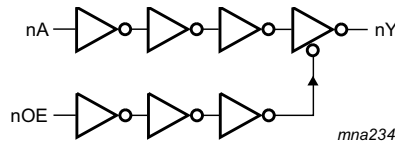


Fig 3. Logic diagram (one buffer/line driver)

## 5. Pinning information

### 5.1 Pinning

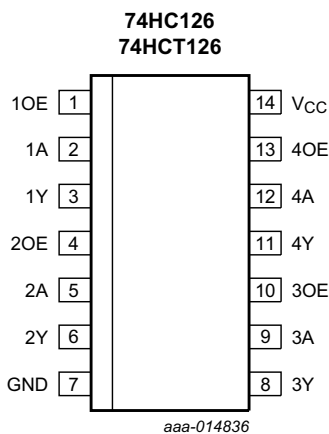


Fig 4. Pin configuration for SOT27-1 and SOT108-1

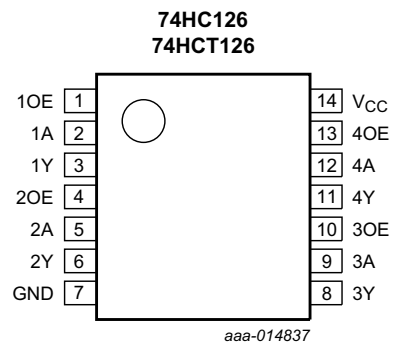


Fig 5. Pin configuration for SOT337-1 and SOT402-1

## 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE, 2OE, 3OE, 4OE	1, 4, 10, 13	data enable input (active HIGH)
1A, 2A, 3A, 4A	2, 5, 9, 12	data input
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	data output
GND	7	ground (0 V)
V <sub>CC</sub>	14	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Control	Input	Output
nOE	nA	nY
H	L	L
H	H	H
L	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	[1]	±20	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V	[1]	±20	mA
I <sub>O</sub>	output current	-0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V	-	±35	mA
I <sub>CC</sub>	supply current		-	70	mA
I <sub>GND</sub>	ground current		-70	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C			
		DIP14 package	[2]	750	mW
		SO14 and (T)SSOP14 packages	[3]	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For DIP14 package: P<sub>tot</sub> derates linearly with 12 mW/K above 70 °C.

[3] For SO14 package: P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.  
For (T)SSOP14 packages: P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74HC126			74HCT126			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC126</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -6.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>OZ</sub>	OFF-state output current	I <sub>O</sub> = 7.8 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V; I <sub>O</sub> = 0 A	-	±0.5	-	±5.0	-	±10	-	μA
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V; I <sub>O</sub> = 0 A	-	±0.5	-	±5.0	-	±10	-	μA

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF
<b>74HCT126</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -6.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 μA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V; I <sub>O</sub> = 0 A	-	-	±0.5	-	±5.0	-	±10	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	8.0	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; I <sub>O</sub> = 0 A; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V; nA, nOE inputs	-	100	360	-	450	-	490	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

GND = 0 V; C<sub>L</sub> = 50 pF; for test circuit, see [Figure 8](#).

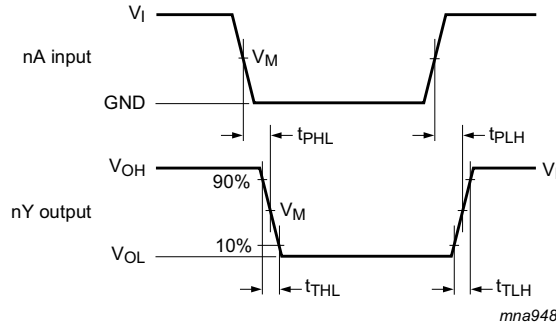
Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
<b>74HC126</b>								
t <sub>pd</sub>	propagation delay	nA to nY; see <a href="#">Figure 6</a> <a href="#">[1]</a>						
		V <sub>CC</sub> = 2.0 V	-	30	100	125	150	ns
		V <sub>CC</sub> = 4.5 V	-	11	20	25	30	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	9	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	-	9	17	21	26	ns

**Table 7. Dynamic characteristics ...continued**  
*GND = 0 V; C<sub>L</sub> = 50 pF; for test circuit, see Figure 8.*

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Max (85 °C)	Max (125 °C)	
t <sub>en</sub>	enable time	nOE to nY; see Figure 7 [1]						
		V <sub>CC</sub> = 2.0 V	-	41	125	155	190	ns
		V <sub>CC</sub> = 4.5 V	-	15	25	31	38	ns
		V <sub>CC</sub> = 6.0 V	-	12	21	26	32	ns
t <sub>dis</sub>	disable time	nOE to nY; see Figure 7 [1]						
		V <sub>CC</sub> = 2.0 V	-	41	125	155	190	ns
		V <sub>CC</sub> = 4.5 V	-	15	25	31	38	ns
		V <sub>CC</sub> = 6.0 V	-	12	21	26	32	ns
t <sub>t</sub>	transition time	see Figure 6 [1]						
		V <sub>CC</sub> = 2.0 V	-	14	60	75	90	ns
		V <sub>CC</sub> = 4.5 V	-	5	12	15	18	ns
		V <sub>CC</sub> = 6.0 V	-	4	10	13	15	ns
C <sub>PD</sub>	power dissipation capacitance	per package; V <sub>I</sub> = GND to V <sub>CC</sub> [2]	-	23	-	-	-	pF
<b>74HCT126</b>								
t <sub>pd</sub>	propagation delay	nA to nY; see Figure 6 [1]						
		V <sub>CC</sub> = 4.5 V	-	14	24	30	36	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	11	-	-	-	ns
t <sub>en</sub>	enable time	nOE to nY; see Figure 7; V <sub>CC</sub> = 4.5 V [1]	-	13	25	31	38	ns
t <sub>dis</sub>	disable time	nOE to nY; see Figure 7; V <sub>CC</sub> = 4.5 V [1]	-	18	28	35	42	ns
t <sub>t</sub>	transition time	V <sub>CC</sub> = 4.5 V; see Figure 6 [1]	-	5	12	15	18	ns
C <sub>PD</sub>	power dissipation capacitance	per package; V <sub>I</sub> = GND to V <sub>CC</sub> - 1.5 V [2]	-	24	-	-	-	pF

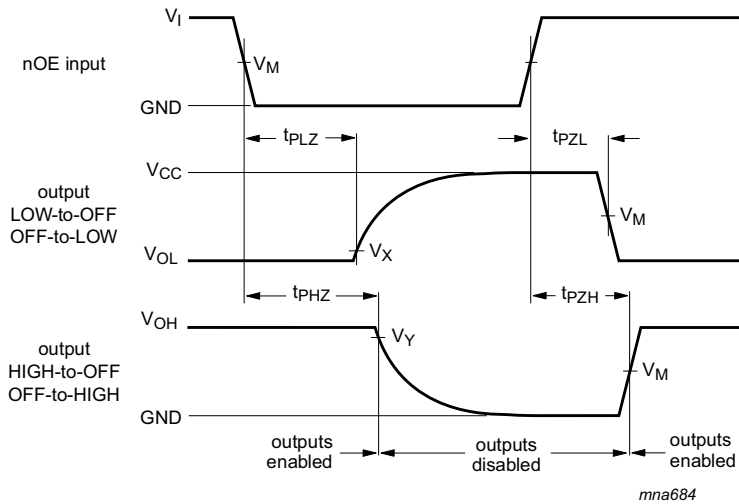
- [1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.  
 t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.  
 t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.  
 t<sub>t</sub> is the same as t<sub>THL</sub> and t<sub>TLH</sub>.
- [2] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:  
 f<sub>i</sub> = input frequency in MHz;  
 f<sub>o</sub> = output frequency in MHz;  
 C<sub>L</sub> = output load capacitance in pF;  
 V<sub>CC</sub> = supply voltage in V;  
 N = number of inputs switching;  
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

11. Waveforms and test circuit



Measurement points are given in [Table 8](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 6. Input (nA) to output (nY) propagation delays**



Measurement points are given in [Table 8](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 7. Enable and disable times**

**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC126	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT126	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$

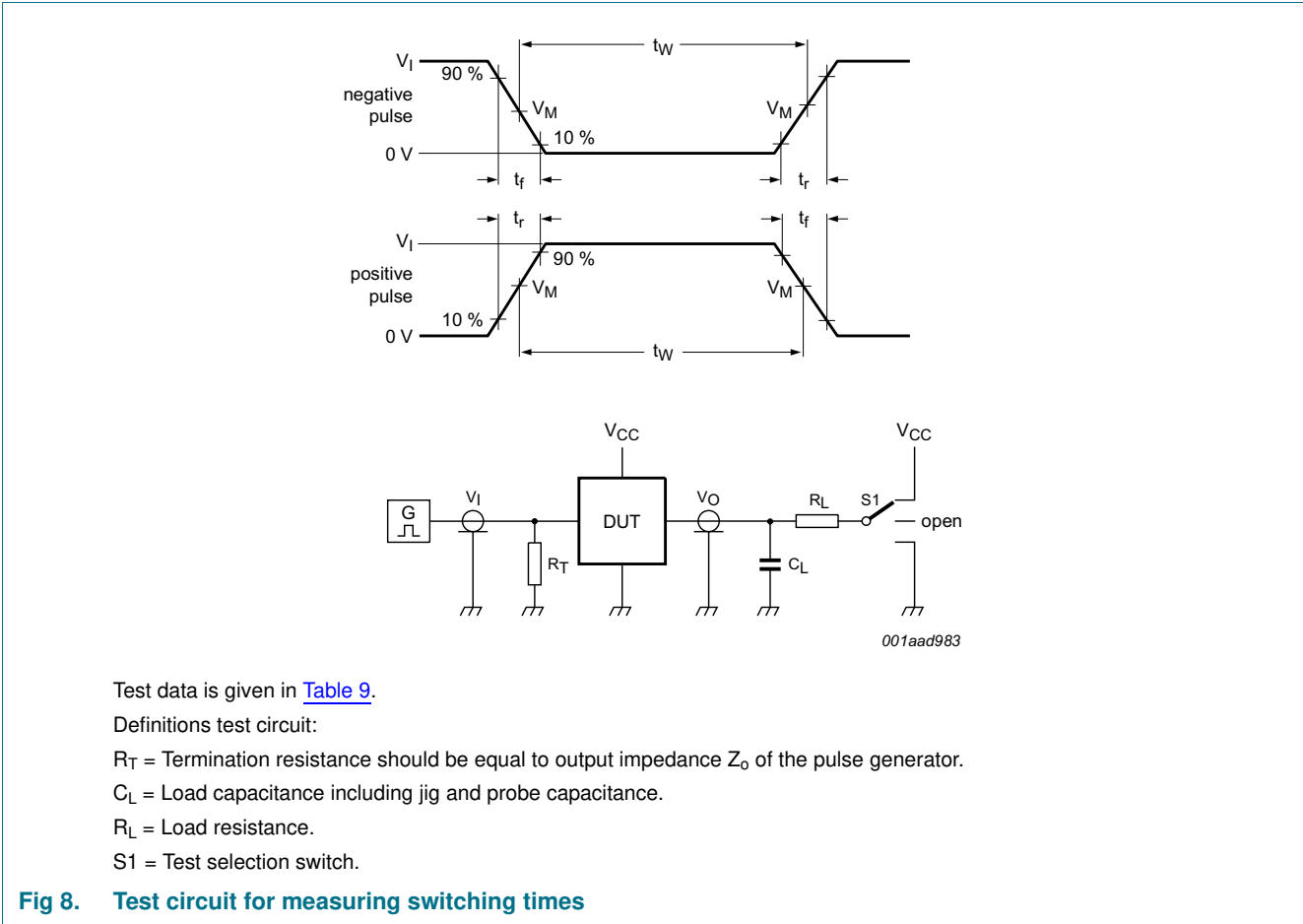


Table 9. Test data

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC126	$V_{CC}$	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT126	3 V	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$



12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

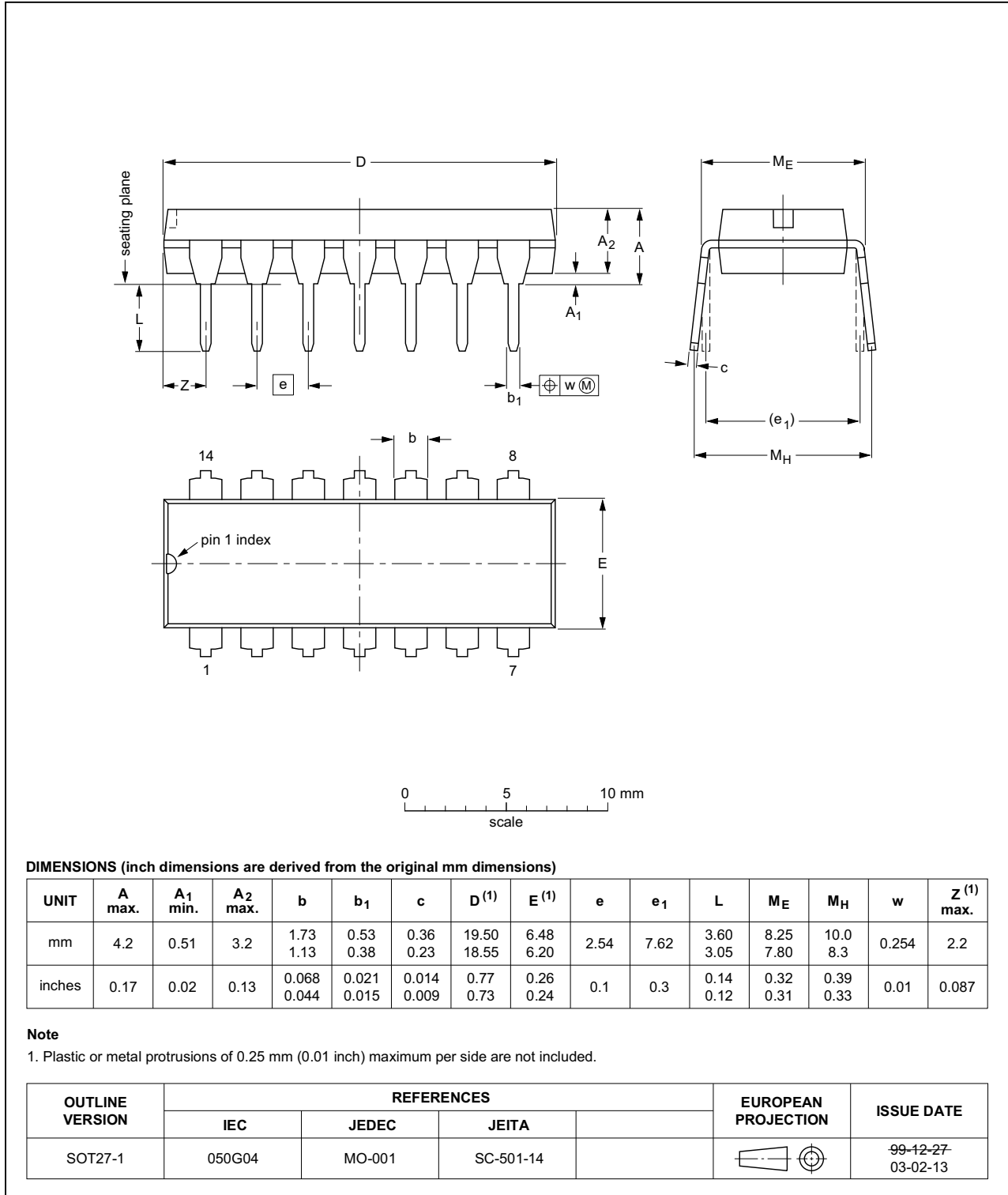


Fig 9. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

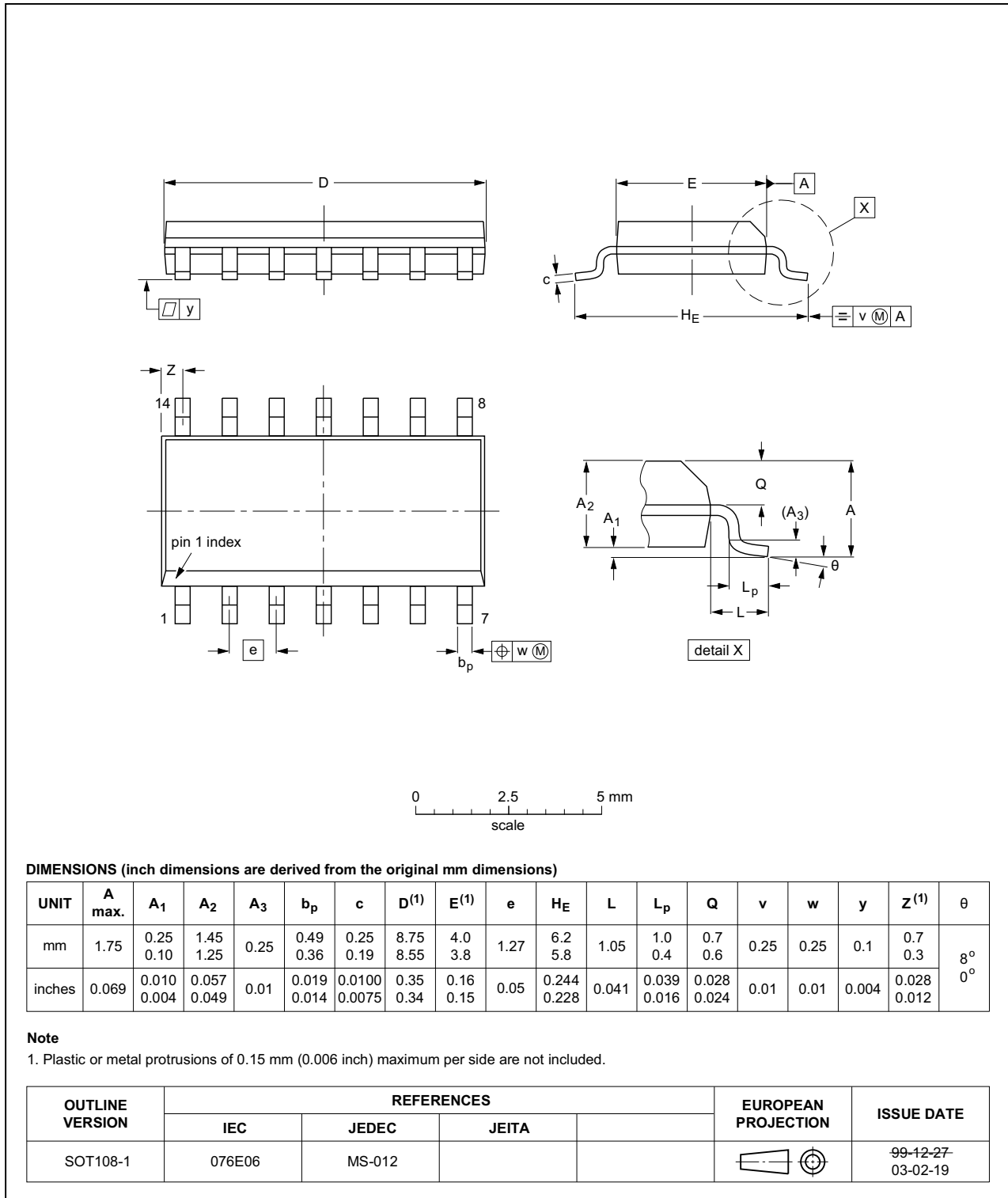


Fig 10. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

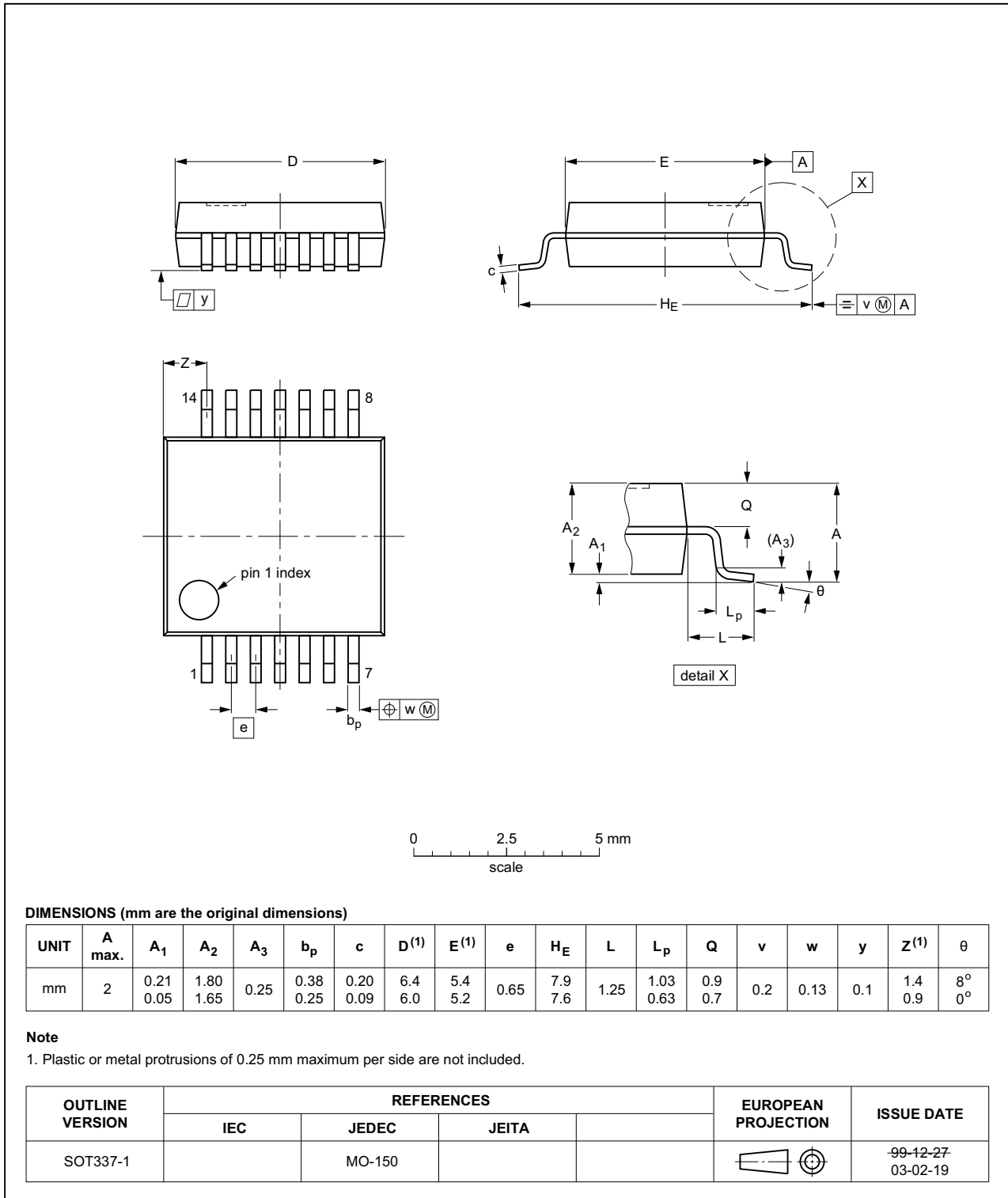


Fig 11. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

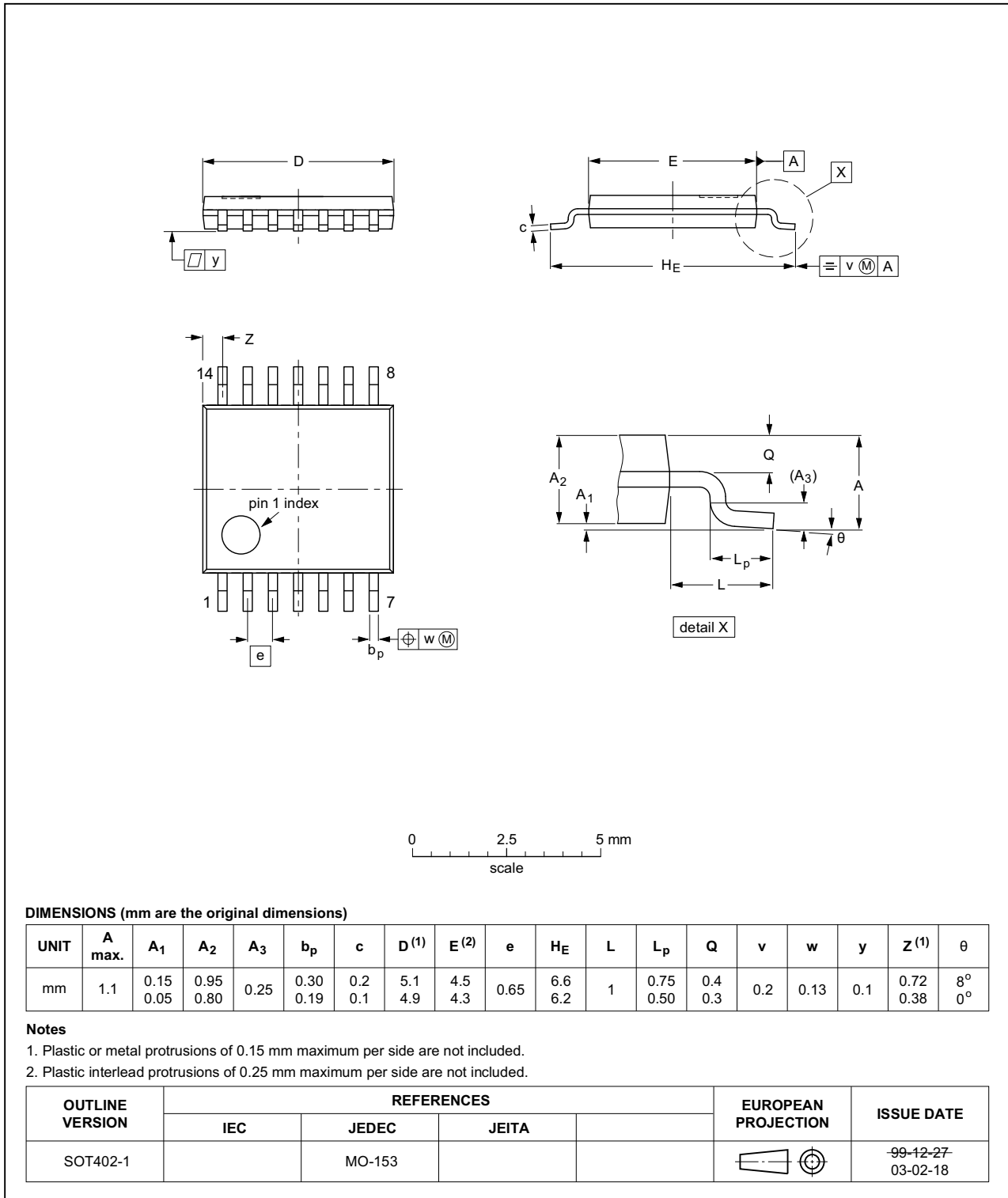


Fig 12. Package outline SOT402-1 (TSSOP14)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT126 v.3	20140922	Product data sheet	-	74HC_HCT126_CNV v.2
Modifications:	<ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul>			
74HC_HCT126_CNV v.2	19901201	Product specification	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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